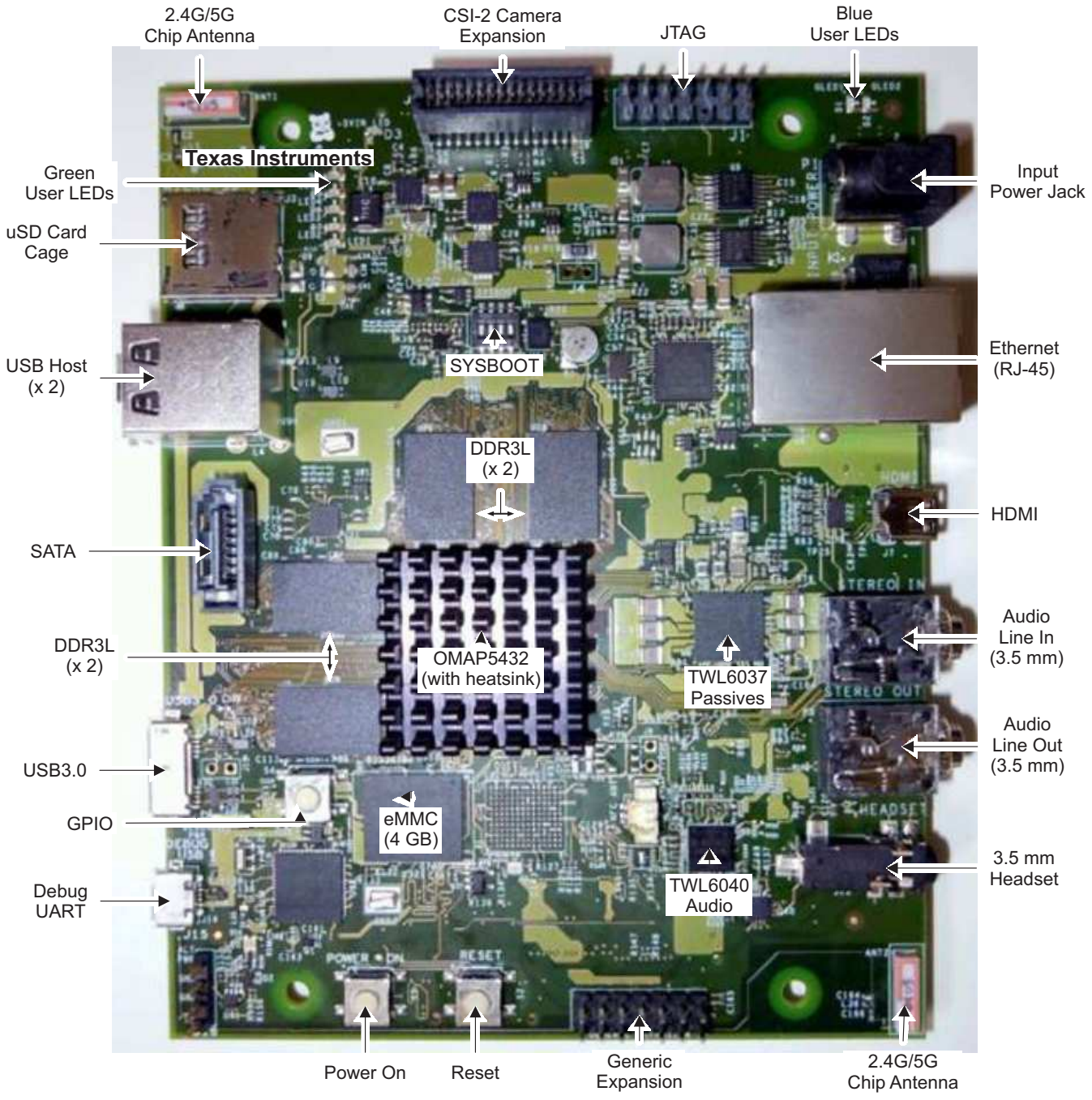
OMAP5432 EVM Quick Start Guide

This document will guide you through the setup of your EVM. This EVM showcases the OMAP™ processor. The following figure highlights various components of the OMAP5432 ES 2.x EVM .

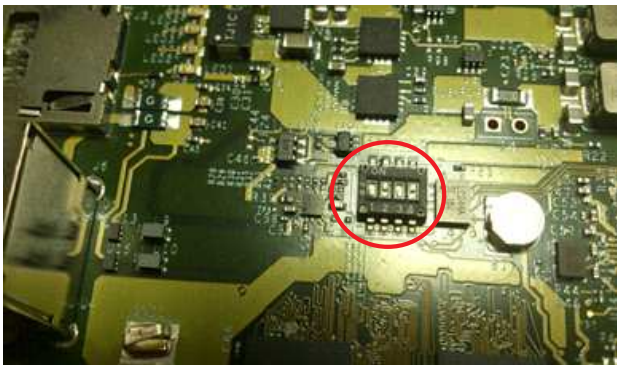


The following items can be used with the OMAP5432 processor-based EVM, but are not included in the kit:

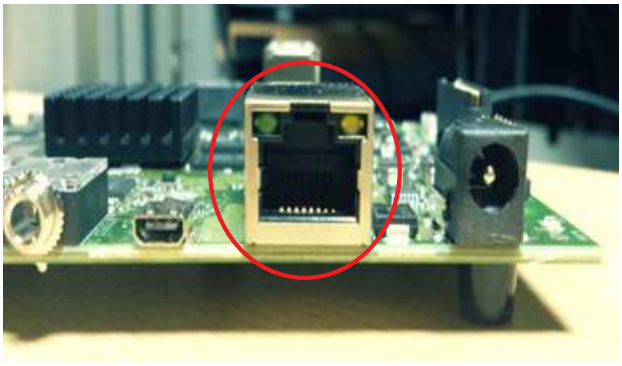
- USB cable (micro-AB to type A)
- HDMI cable (type D)
- Mini-display port cable
- DC wall supply (+12Vdc)

Default Linux® Setup

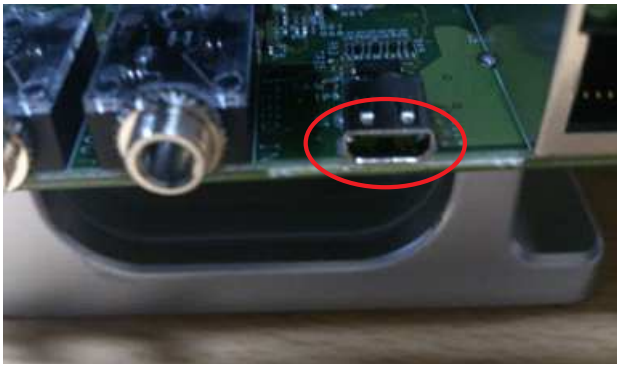
The procedure listed in this document is the default setup for a Linux boot from a SD card.



1. For SD boot set up, configure Sysboot Switch (near the RJ-45 jack) which is numbered 1 to 4 as SYSBOOT[4:1] = 1010



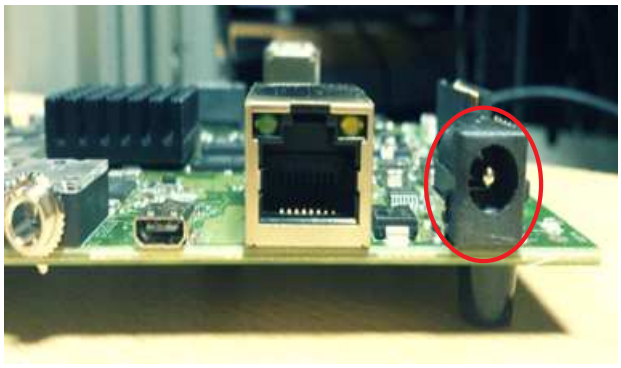
2. Connect the Ethernet cable to the RJ-45 jack on the board. Connect the other end of the cable to an Internet-ready connection.



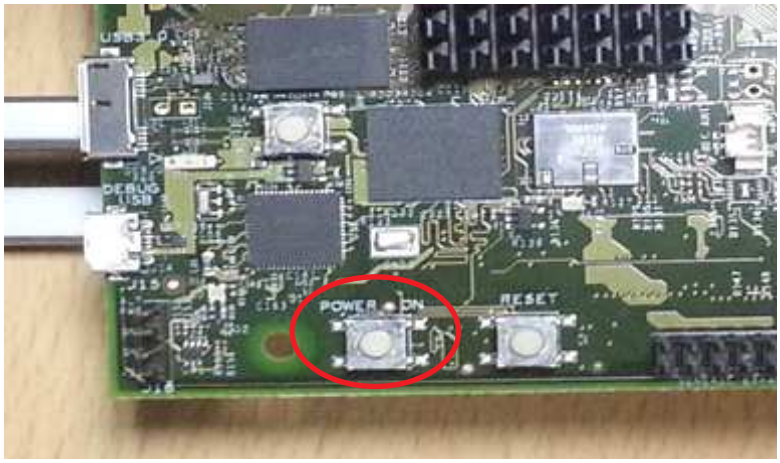
3. For display, user will need to provide an external monitor with an HDMI input. Connect a HDMI Cable (Type D) to the HDMI connector. Connect the other end of the cable to the user-supplied monitor.

4. Create a micro SD card following the steps as explained in the Software Developers' Guide section 2.2 Prepare SD Card. Insert the micro SD card into the SD card slot, with Micro SD card label facing up.

5. Connect a Debug USB via micro-USB connector via micro USB port (J15). Connect the other end of the serial cable to a PC. This step is optional. This step enables viewing of console messages on a PC terminal and changing some of the default parameters on the board.



6. Connect the supplied 12-V DC power supply to the EVM (P1).



7. Press the Power On button (S3) and verify if the blue LED lights turn on.

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